

Conventional FR-4/Normal Tg/CTI>600

特性 (Feature)

- 兼容紫外光阻挡及光学自动检查功能
UVB and AOI (automatic optical inspection) compatible
- 优良的耐热性能和机械性能
Excellent heat resistance and mechanical properties
- 符合IPC-4101E/97的规范要求
IPC-4101E/97 specification is applicable
- CTI≥600

应用 (Application)

- 计算机及外围设备
Computer and peripheral
- 通讯设备
Communication equipment
- 仪器仪表
Instrument
- 办公自动设备等
OA equipment, etc.

板材性能 (Laminate Properties)

Test Item 测试项目		Test Method (IPC-TM- 650) 测试方法	Test Condition 处理条件	Unit 单位	Specification 规格值 (IPC-4101E/97)	Typical Value 典型值	
Thermal 热性能	Thermal Stress 热应力	2.4.13.1	Float 288 °C/ Unetched	Sec	≥10	≥180	
	Glass Transition (Tg) 玻璃化转变温度	2.4.25	E-2/105 DSC	°C	≥130	135	
	CTE/ Z-Axis Expansion Z-轴热膨胀系数	2.4.24	Alpha 1	ppm/°C	—	45	
			Alpha 2		—	240	
	T-260	2.4.24.1	TMA	min	—	> 20	
	TD(5% weight loss)	2.4.24.6	TGA	°C	—	314	
Flammability 燃烧性	UL94	E-24/ 23	Rating	V-0	V-0		
Electrical 电性能	Surface Resistivity 表面电阻	2.5.17.1	C-96/35/90	MΩ	≥10 ⁴	1.0×10 ⁷	
	Volume Resistivity 体积电阻	2.5.17.1	C-96/35/90	MΩ-cm	≥10 ⁶	1.0×10 ⁹	
	Dielectric Breakdown 击穿电压	2.5.6	D-48/ 50+D-0.5/ 23	kV	≥40	69	
	Dielectric Constant 介电常数	2.5.5.2	Etched (RC50%)	@ 1 MHz	—	≤5.4	4.7
				@ 1 GHz			4.6
	Loss Tangent 介质损耗	2.5.5.2	Etched (RC50%)	@ 1 MHz	—	≤0.035	0.014
				@ 1 GHz			0.015
CTI 相对漏电起痕指数	IEC60112	A	V	—	≥600		
Arc Resistance 耐电弧性	2.5.1	D-48/ 50+D-0.5/ 23	Sec	≥60	125		
Mechanical 机械性能	Peel Strength (1 oz.) 铜箔剥离强度	2.4.8	125 °C	N/mm	≥0.70	1.6	
			Float 288 °C/ 10 Sec		≥1.05	1.7	
			After Process Solution		≥0.80	1.25	
	Flexural Strength 抗弯强度	2.4.4	Length Direction	N/mm ²	≥415	565	
			Cross Direction		≥345	416	
Moisture Absorption 吸水率	2.6.2.1	D-24/23	%	≤0.5	0.19		

KB-6160C 板材清单 (Laminate List)

Thickness 厚度 (mm)	Size 尺寸 (Inch)	Copper foil Type 铜箔类型
0.05-3.20	37" x49" , 41" x49" , 43" x49" 74" x49" , 82" x49" , 86" x49"	Reverse treated copper foil RTF铜箔 : 1/3OZ—3OZ HTE copper foil HTE铜箔 : 1/3OZ—3OZ

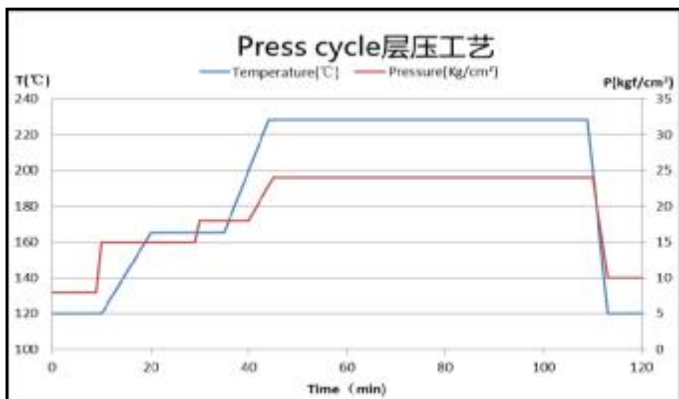
KB-6060C 半固化片清单 (Prepreg List)

UL Designation UL型号	PP style 类型	R/C(%) 树脂含量	Dk±0.2(1GHz) 介电常数	Df±10%(1GHz) 介质损耗	Thickness(mil) 压合厚度
KB-6060C	1080	62±2	4.3	0.016	2.8±0.30
		65±2	4.2	0.017	3.1±0.40
		68±2	4.2	0.017	3.4±0.40
	3313	55±2	4.5	0.017	3.8±0.30
		58±2	4.4	0.017	4.2±0.40
	2116	52±2	4.5	0.016	4.6±0.40
		55±2	4.5	0.016	5.0±0.40
		58±2	4.4	0.016	5.4±0.50
	1506	46±2	4.6	0.015	6.2±0.40
		50±2	4.5	0.016	6.8±0.50
	7628	43±2	4.7	0.015	7.3±0.40
		45±2	4.6	0.015	7.7±0.50
48±2		4.6	0.015	8.3±0.50	

KB-6060C 半固化片储存 (Prepreg Storage)

储存条件(Condition)	有效期(Shelf Life)
Max. 50%RH & Max. 23°C 湿度 < 50% 及 温度 < 23°C	90 days
Max. 5°C(Normal in room temperature for at least 4h before using) 温度 < 5°C (拆包装前需在室温下回温至少4小时)	180 days

压合参数(Recommended Process)



- Heat-up rate: 1.0-2.5 °C/ min (80 °C-140 °C)
热压升温速率: 1.0-2.5 °C/ min (80 °C-140 °C)
- Curing time: >45min (>175 °C)
固化时间: >45min (>175 °C)
- Curing pressure: 25±5 kgf/ cm²
(Vacuum Hydraulic Press)
固化压力: 25±5 kgf/ cm²
(真空液压机)